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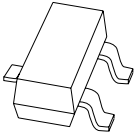
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Kind regards,

Team Nexperia



PMEGxx05ET series

0.5 A very low V_F MEGA Schottky barrier rectifiers in SOT23 package

Rev. 02 — 13 January 2010

Product data sheet

1. Product profile

1.1 General description

Planar Maximum Efficiency General Application (MEGA) Schottky barrier rectifier with an integrated guard ring for stress protection, encapsulated in a SOT23 small Surface Mounted Device (SMD) plastic package.

Table 1. Product overview

| Type number | Package | | Configuration |
|-------------|---------|-------|---------------|
| | NXP | JEITA | |
| PMEG2005ET | SOT23 | - | single diode |
| PMEG3005ET | SOT23 | - | single diode |
| PMEG4005ET | SOT23 | - | single diode |

1.2 Features

- Forward current: 0.5 A
- Very low forward voltage
- Small SMD plastic package

1.3 Applications

- Low voltage rectification
- High efficiency DC-to-DC conversion
- Switch mode power supply
- Inverse polarity protection
- Low power consumption applications

1.4 Quick reference data

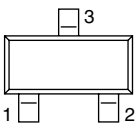
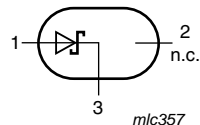
Table 2. Quick reference data

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|--------|-----------------|------------------------|-----|-----|-----|------|
| I_F | forward current | | - | - | 0.5 | A |
| V_R | reverse voltage | | | | | |
| | PMEG2005ET | | - | - | 20 | V |
| | PMEG3005ET | | - | - | 30 | V |
| | PMEG4005ET | | - | - | 40 | V |
| V_F | forward voltage | $I_F = 500 \text{ mA}$ | [1] | | | |
| | PMEG2005ET | | - | 355 | 390 | mV |
| | PMEG3005ET | | - | 380 | 430 | mV |
| | PMEG4005ET | | - | 420 | 470 | mV |

[1] Pulse test: $t_p \leq 300 \mu\text{s}$; $\delta \leq 0.02$.

2. Pinning information

Table 3. Pinning

| Pin | Description | Simplified outline | Symbol |
|-----|---------------|---|---|
| 1 | anode |  |  |
| 2 | not connected | | |
| 3 | cathode | | |

3. Ordering information

Table 4. Ordering information

| Type number | Package | | |
|-------------|---------|--|---------|
| | Name | Description | Version |
| PMEG2005ET | - | plastic surface mounted package; 3 leads | SOT23 |
| PMEG3005ET | - | plastic surface mounted package; 3 leads | SOT23 |
| PMEG4005ET | - | plastic surface mounted package; 3 leads | SOT23 |

4. Marking

Table 5. Marking codes

| Type number | Marking code ^[1] |
|-------------|-----------------------------|
| PMEG2005ET | P3* |
| PMEG3005ET | P4* |
| PMEG4005ET | P5* |

- [1] * = -: made in Hong Kong
 * = p: made in Hong Kong
 * = t: made in Malaysia
 * = W: made in China

5. Limiting values

Table 6. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol | Parameter | Conditions | Min | Max | Unit |
|-----------|-------------------------------------|--|-------|------|------------------|
| V_R | reverse voltage | | | | |
| | PMEG2005ET | | - | 20 | V |
| | PMEG3005ET | | - | 30 | V |
| | PMEG4005ET | | - | 40 | V |
| I_F | forward current | | - | 0.5 | A |
| I_{FRM} | repetitive peak forward current | $t_p \leq 1 \text{ ms}; \delta \leq 0.5$ | - | 3.9 | A |
| I_{FSM} | non-repetitive peak forward current | $t_p = 8 \text{ ms square wave}$ | [1] - | 10 | A |
| P_{tot} | total power dissipation | $T_{amb} \leq 25 \text{ }^\circ\text{C}$ | [1] - | 280 | mW |
| | | | [2] - | 420 | mW |
| T_j | junction temperature | | - | 150 | $^\circ\text{C}$ |
| T_{amb} | ambient temperature | | -65 | +150 | $^\circ\text{C}$ |
| T_{stg} | storage temperature | | -65 | +150 | $^\circ\text{C}$ |

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm².

6. Thermal characteristics

Table 7. Thermal characteristics

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|---------------|---|-------------|----------|-----|-----|------|
| $R_{th(j-a)}$ | thermal resistance from junction to ambient | in free air | [1][2] - | - | 440 | K/W |
| | | | [1][3] - | - | 300 | K/W |

[1] For Schottky barrier diodes thermal run-away has to be considered, as in some applications the reverse power losses P_R are a significant part of the total power losses. Nomograms for determining the reverse power losses P_R and $I_{F(AV)}$ rating will be available on request.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm².

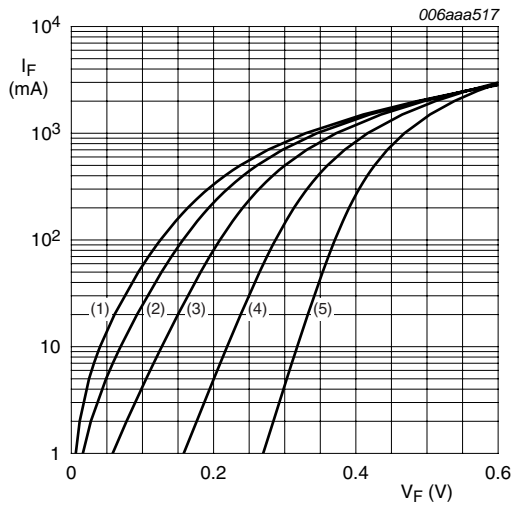
7. Characteristics

Table 8. Characteristics

$T_{amb} = 25\text{ }^{\circ}\text{C}$ unless otherwise specified.

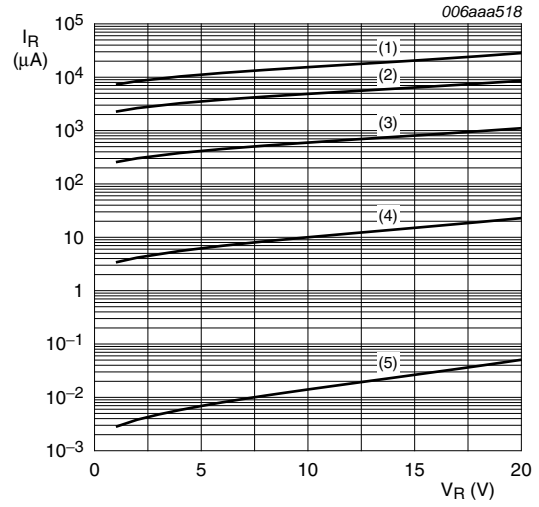
| Symbol | Parameter | Conditions | Min | Typ | Max | Unit | | | |
|---------------------|---------------------|--------------------------------------|-----------------------|------------|---------------------|------|---------------|-----|---------------|
| V_F | forward voltage | | | | | [1] | | | |
| | | PMEG2005ET | $I_F = 0.1\text{ mA}$ | - | 90 | 130 | mV | | |
| | | | $I_F = 1\text{ mA}$ | - | 150 | 190 | mV | | |
| | | | $I_F = 10\text{ mA}$ | - | 210 | 240 | mV | | |
| | | | $I_F = 100\text{ mA}$ | - | 280 | 330 | mV | | |
| | | | $I_F = 500\text{ mA}$ | - | 355 | 390 | mV | | |
| | | PMEG3005ET | $I_F = 0.1\text{ mA}$ | - | 90 | 130 | mV | | |
| | | | $I_F = 1\text{ mA}$ | - | 150 | 200 | mV | | |
| | | | $I_F = 10\text{ mA}$ | - | 215 | 250 | mV | | |
| | | | $I_F = 100\text{ mA}$ | - | 285 | 340 | mV | | |
| | | | $I_F = 500\text{ mA}$ | - | 380 | 430 | mV | | |
| | | PMEG4005ET | $I_F = 0.1\text{ mA}$ | - | 95 | 130 | mV | | |
| | | | $I_F = 1\text{ mA}$ | - | 155 | 210 | mV | | |
| | | | $I_F = 10\text{ mA}$ | - | 220 | 270 | mV | | |
| | | | $I_F = 100\text{ mA}$ | - | 295 | 350 | mV | | |
| | | | $I_F = 500\text{ mA}$ | - | 420 | 470 | mV | | |
| | | I_R | reverse current | PMEG2005ET | $V_R = 10\text{ V}$ | - | 15 | 40 | μA |
| | | | | | $V_R = 20\text{ V}$ | - | 40 | 200 | μA |
| | | | | PMEG3005ET | $V_R = 10\text{ V}$ | - | 12 | 30 | μA |
| $V_R = 30\text{ V}$ | - | | | | 40 | 150 | μA | | |
| PMEG4005ET | $V_R = 10\text{ V}$ | | | - | 7 | 20 | μA | | |
| | $V_R = 40\text{ V}$ | | | - | 30 | 100 | μA | | |
| C_d | diode capacitance | $V_R = 1\text{ V}; f = 1\text{ MHz}$ | PMEG2005ET | - | 66 | 80 | pF | | |
| | | | PMEG3005ET | - | 55 | 70 | pF | | |
| | | | PMEG4005ET | - | 43 | 50 | pF | | |

[1] Pulse test: $t_p \leq 300\text{ }\mu\text{s}$; $\delta \leq 0.02$.



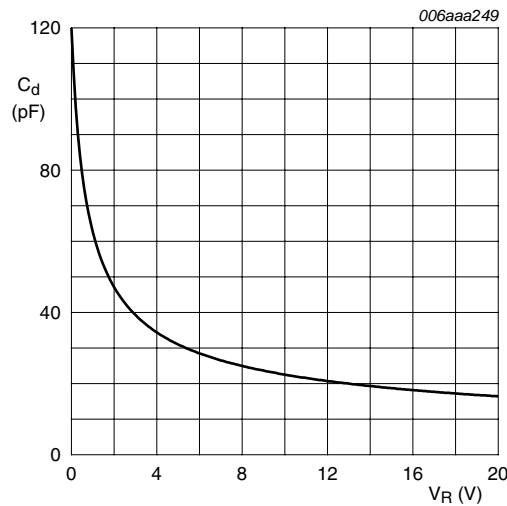
- (1) $T_{amb} = 150\text{ °C}$
- (2) $T_{amb} = 125\text{ °C}$
- (3) $T_{amb} = 85\text{ °C}$
- (4) $T_{amb} = 25\text{ °C}$
- (5) $T_{amb} = -40\text{ °C}$

Fig 1. PMEG2005ET: Forward current as a function of forward voltage; typical values



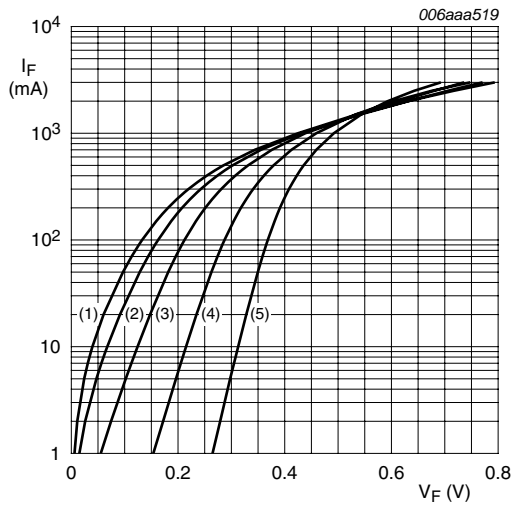
- (1) $T_{amb} = 150\text{ °C}$
- (2) $T_{amb} = 125\text{ °C}$
- (3) $T_{amb} = 85\text{ °C}$
- (4) $T_{amb} = 25\text{ °C}$
- (5) $T_{amb} = -40\text{ °C}$

Fig 2. PMEG2005ET: Reverse current as a function of reverse voltage; typical values



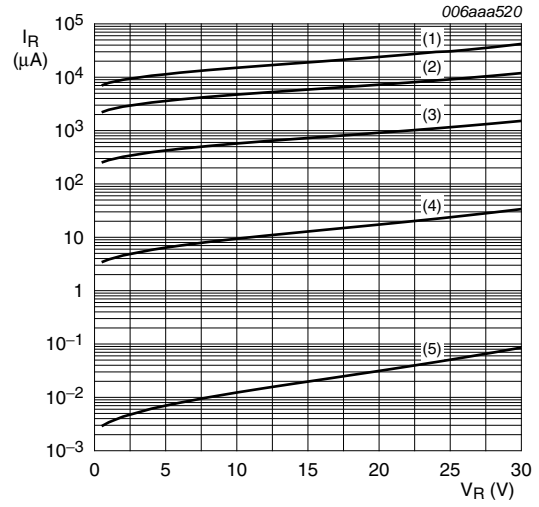
$T_{amb} = 25\text{ °C}; f = 1\text{ MHz}$

Fig 3. PMEG2005ET: Diode capacitance as a function of reverse voltage; typical values



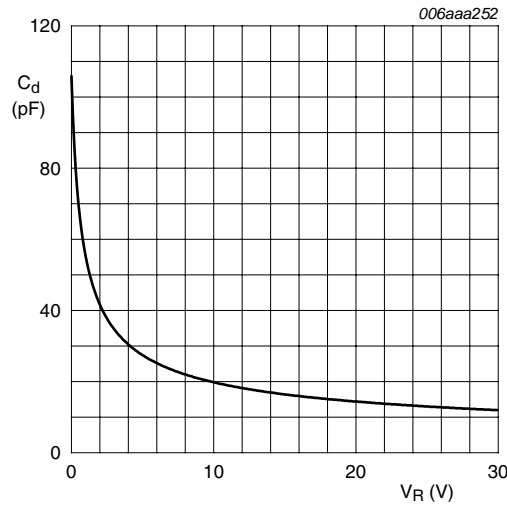
- (1) $T_{amb} = 150\text{ °C}$
- (2) $T_{amb} = 125\text{ °C}$
- (3) $T_{amb} = 85\text{ °C}$
- (4) $T_{amb} = 25\text{ °C}$
- (5) $T_{amb} = -40\text{ °C}$

Fig 4. PMEG3005ET: Forward current as a function of forward voltage; typical values



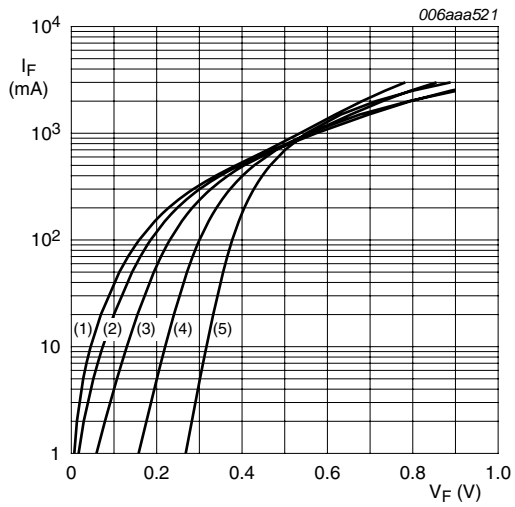
- (1) $T_{amb} = 150\text{ °C}$
- (2) $T_{amb} = 125\text{ °C}$
- (3) $T_{amb} = 85\text{ °C}$
- (4) $T_{amb} = 25\text{ °C}$
- (5) $T_{amb} = -40\text{ °C}$

Fig 5. PMEG3005ET: Reverse current as a function of reverse voltage; typical values



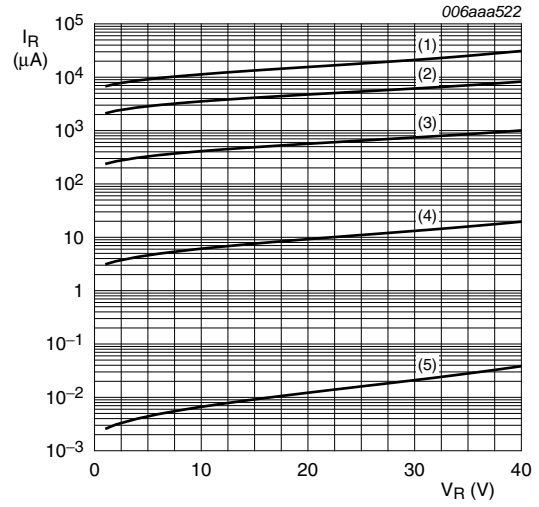
$T_{amb} = 25\text{ °C}; f = 1\text{ MHz}$

Fig 6. PMEG3005ET: Diode capacitance as a function of reverse voltage; typical values



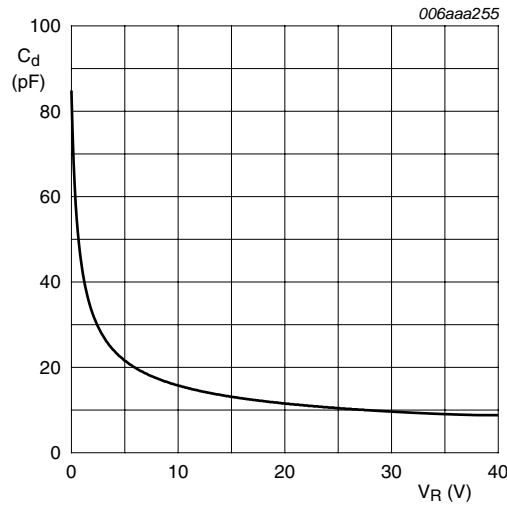
- (1) $T_{amb} = 150\text{ °C}$
- (2) $T_{amb} = 125\text{ °C}$
- (3) $T_{amb} = 85\text{ °C}$
- (4) $T_{amb} = 25\text{ °C}$
- (5) $T_{amb} = -40\text{ °C}$

Fig 7. PMEG4005ET: Forward current as a function of forward voltage; typical values



- (1) $T_{amb} = 150\text{ °C}$
- (2) $T_{amb} = 125\text{ °C}$
- (3) $T_{amb} = 85\text{ °C}$
- (4) $T_{amb} = 25\text{ °C}$
- (5) $T_{amb} = -40\text{ °C}$

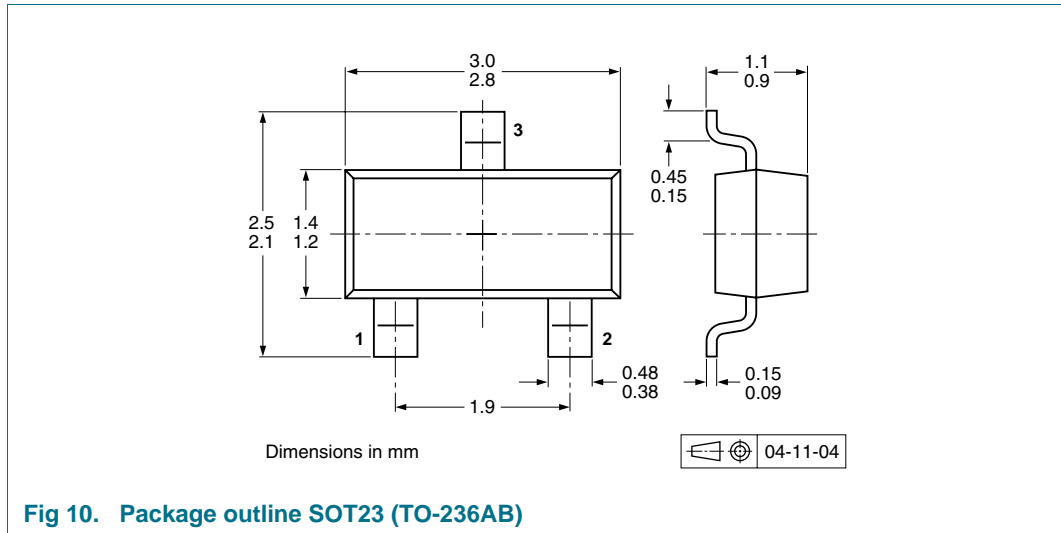
Fig 8. PMEG4005ET: Reverse current as a function of reverse voltage; typical values



$T_{amb} = 25\text{ °C}; f = 1\text{ MHz}$

Fig 9. PMEG4005ET: Diode capacitance as a function of reverse voltage; typical values

8. Package outline



9. Packing information

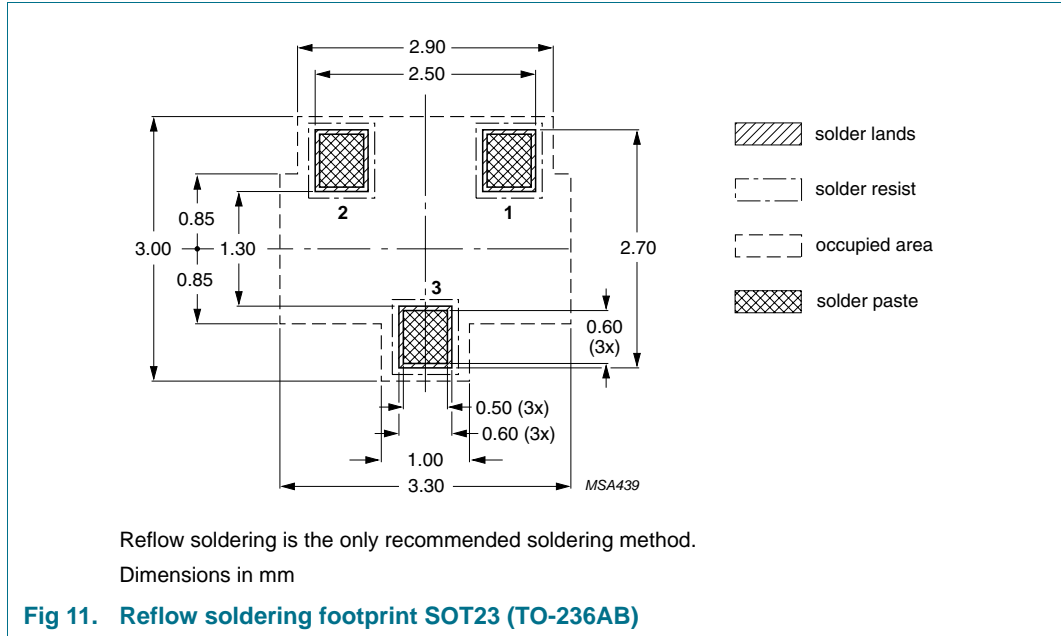
Table 9. Packing methods

The -xxx numbers are the last three digits of the 12NC ordering code.^[1]

| Type number | Package | Description | Packing quantity | |
|-------------|---------|--------------------------------|------------------|-------|
| | | | 3000 | 10000 |
| PMEG2005ET | SOT23 | 4 mm pitch, 8 mm tape and reel | -215 | -235 |
| PMEG3005ET | | | | |
| PMEG4005ET | | | | |

[1] For further information and the availability of packing methods, see [Section 13](#).

10. Soldering



11. Revision history

Table 10. Revision history

| Document ID | Release date | Data sheet status | Change notice | Supersedes |
|------------------|--------------|--|---------------|------------------|
| PMEGXX05ET_SER_2 | 20100113 | Product data sheet | - | PMEGXX05ET_SER_1 |
| Modifications: | | <ul style="list-style-type: none">This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content.Figure 11 "Reflow soldering footprint SOT23 (TO-236AB)"; updated | | |
| PMEGXX05ET_SER_1 | 20050715 | Product data sheet | - | - |

12. Legal information

12.1 Data sheet status

| Document status ^{[1][2]} | Product status ^[3] | Definition |
|-----------------------------------|-------------------------------|---|
| Objective [short] data sheet | Development | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet | Qualification | This document contains data from the preliminary specification. |
| Product [short] data sheet | Production | This document contains the product specification. |

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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